Advanced Controls Added to Liebert XDC Refrigerant Chiller

In an effort to help data center managers increase control and operating efficiency of their precision cooling systems, Emerson Network Power has added Liebert iCOM controls to the Liebert XDC refrigerant chiller. The Liebert XDC with iCOM is available in North America, South America, Europe, China, India, Middle East and Africa.

Providing refrigerant circulation and control in applications where the building's chilled water system is not available, the Liebert XDC with iCOM can cool more than 30 kW per rack and 160 kW per system. The Liebert XDC with iCOM is designed to support the Liebert XD Smart Modules, which are cooling modules that are compatible with the Liebert XD family and feature integrated control boards that enable modulation of cooling capacity and higher efficiency performance. With dynamic fan control, the Liebert XD Smart modules can save 50 to 70 percent in energy costs over traditional precision cooling methods.

The Liebert XDC refrigerant chiller, the only one of its kind, supports the Liebert XD family of high heat density cooling solutions—the Liebert XDV rack-mount, Liebert XDO ceiling-mount, Liebert XDH row-based and Liebert XDR rear door cooling modules. The Liebert XD refrigerant-based cooling modules, the industry's first pumped refrigerant solution when introduced, work as a system to support the hot aisle/cold aisle approach to cooling high density data centers. The addition of Liebert iCOM controls to the Liebert XD family of cooling solutions increases the flexibility of the data center.

The Liebert XDC with iCOM and the Liebert XDP with iCOM now employ a controller-area network (CAN-bus) configuration, enabling a new communications network bridging a data center's building management system (BMS) or data center infrastructure management (DCIM) system to Liebert XD Smart Module level. Liebert iCOM with CAN-bus communications allows real-time monitoring and data capture of supply and return air temperatures at the rack level, module cooling capacity and fan status and presents the data in graphical views that easily convey data center conditions to users. Status may be reported back to the DCIM or BMS via Liebert IntelliSlot communications cards. An upgrade kit is available for currently installed Liebert XDC and Liebert XDP units to utilize the CAN-bus communication between the Liebert XD Smart Modules and BMS or DCIM.

"The enhanced level of communications and control empowers data center and facilities managers to optimize cooling capacity at the rack level, and to make intelligent decisions surrounding their data center operating environment in real-time, without guessing or waiting for a problem to occur," said Fred Stack, vice president marketing for the Liebert precision cooling business of Emerson Network Power in North America. "With this level of insight, managers can better monitor

cooling performance and eliminate hot spots in the rack caused by high density deployments, as well as make strategic decisions on deployment of in-rack servers based on capacity needs."

"The Liebert XDP and XDC with Liebert iCOM controls provide a precision cooling platform that integrates with our building management system and provides dynamic, real-time temperature monitoring in our data center," said Stuart Cohnen, data center systems engineer at a major research university that utilizes the Liebert equipment in its 1,000 square foot data center located in New York City. "The additional information and control are a tremendous help when it comes to data center planning and decision making."

For more information on the Liebert XDC and Liebert XD family of high heat density cooling solutions, or any other Liebert technologies and services from Emerson Network Power, visit www.Liebert.com [1].

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[1] http://www.Liebert.com